



Material Content Data Sheet



Sales Product Name		BTS5030-2EKA		Issued		19. April 2016		
MA#		MA001066656						
Package		PG-DSO-14-40		Weight*		149.85 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.425	2.29	2.29	22853	22853
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		464	
	non noble metal	iron	7439-89-6	1.392	0.93		9288	
wire	non noble metal	copper	7440-50-8	56.512	37.71	38.70	377127	386995
	non noble metal	copper	7440-50-8	0.955	0.64	0.64	6373	6373
	encapsulation	organic material	carbon black	1333-86-4	0.168	0.11		1119
plastics	plastics	epoxy resin	-	7.711	5.15		51462	
	inorganic material	silicondioxide	60676-86-0	75.941	50.66	55.92	506788	559369
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8183	8183
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9460	9460
glue	plastics	epoxy resin	-	0.177	0.12		1184	
	noble metal	silver	7440-22-4	0.837	0.56	0.68	5583	6767
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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